



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET**TFD150N04M****• General Description**

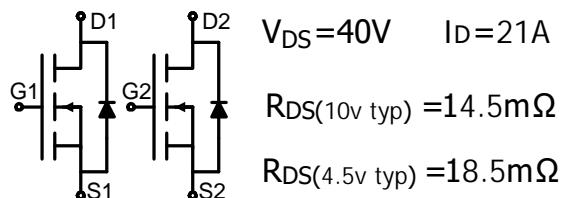
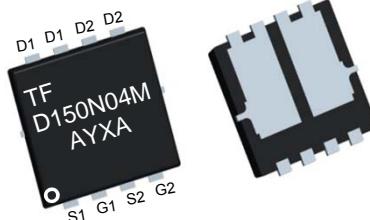
The TFD150N04M combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON). This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low RDS(ON) to minimize conductive loss
- Low Gate Charge for fast switching
- Dual DIE in one package

• Application

- Power Management in Notebook Computer,
- Portable Equipment and Battery
- Powered Systems

• Product Summary $V_{DS}=40V$ $I_D=21A$ $R_{DS(10v\ typ)}=14.5m\Omega$ $R_{DS(4.5v\ typ)}=18.5m\Omega$ **PDFN3333-8****• Package Marking and Ordering Information:**

Part NO.	TFD150N04M
Marking1	TFD150N04M
Marking2	TF:tuofeng; Y:year code; X:Week; AA:device code;
Basic ordering unit (pcs)	5000

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D@T_C=25^\circ C$	21	A
	$I_D@T_C=75^\circ C$	14.7	A
	$I_D@T_C=100^\circ C$	12.6	A
Pulsed Drain Current ^①	I_{DM}	60	A
Total Power Dissipation	$P_D@T_C=25^\circ C$	20	W
Total Power Dissipation	$P_D@T_A=25^\circ C$	1.2	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	40	mJ



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD150N04M

• Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	4.0	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	68	° C/W
Soldering temperature, wavesoldering for 8 s	T _{sold}	-	-	265	° C

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	40	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA	1.0	1.5	2.0	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =40 V _{GS} = 0V	-	-	1.0	μA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} = 0V	-	-	±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A	-	14.5	18	mΩ
		V _{GS} =4.5V, I _D =6A	-	18.5	23	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 25V, I _D =8A	-	8	-	S
Source-drain voltage	V _{SD}	I _S =8A	-	-	1.20	V

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz V _{DS} =20V V _{GS} =0V	-	518	-	pF
Output capacitance	C _{oss}		-	22.2	-	
Reverse transfer capacitance	C _{rss}		-	30.8	-	

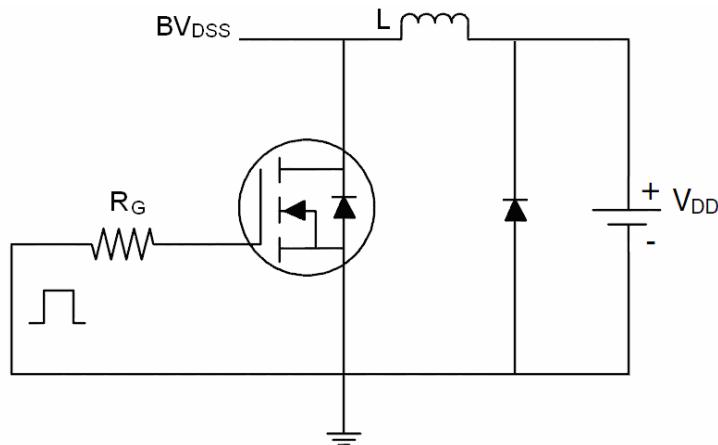
• Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DD} = 20V I _D = 8A V _{GS} = 10V	-	14.3	-	nC
Gate - Source charge	Q _{gs}		-	2.36	-	
Gate - Drain charge	Q _{gd}		-	2.58	-	

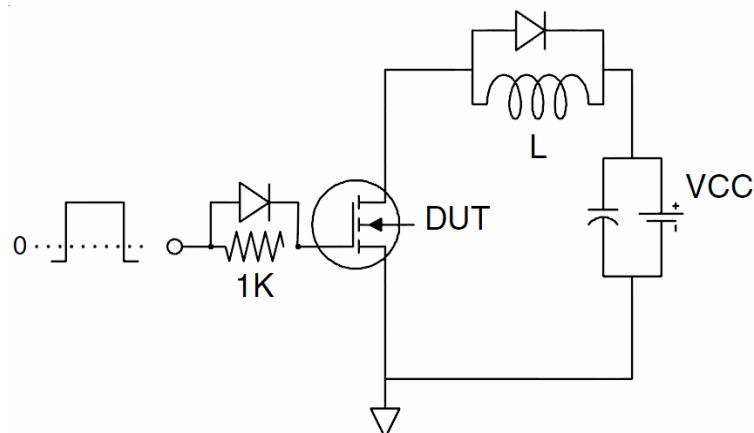
Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Test Circuit

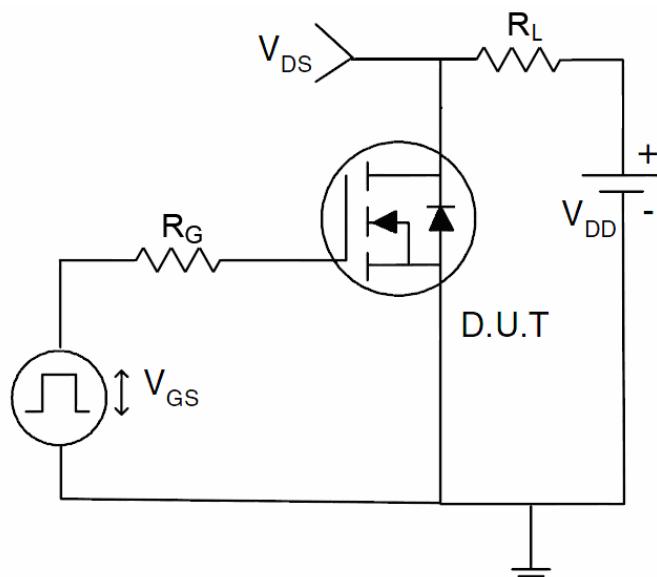
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



N -CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD150N04M

Typical Electrical and Thermal Characteristics

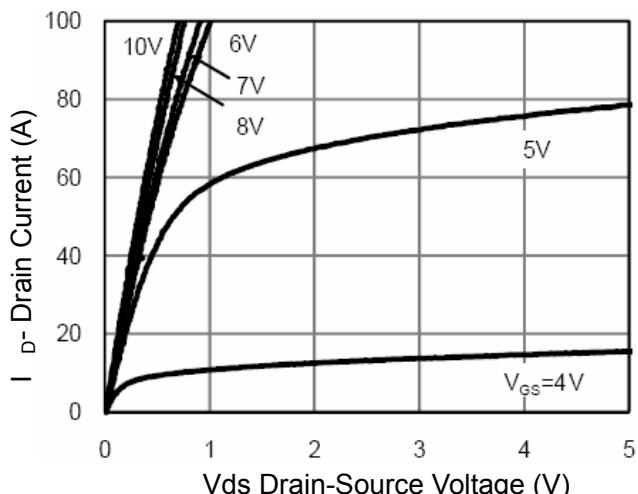


Figure 1 Output Characteristics

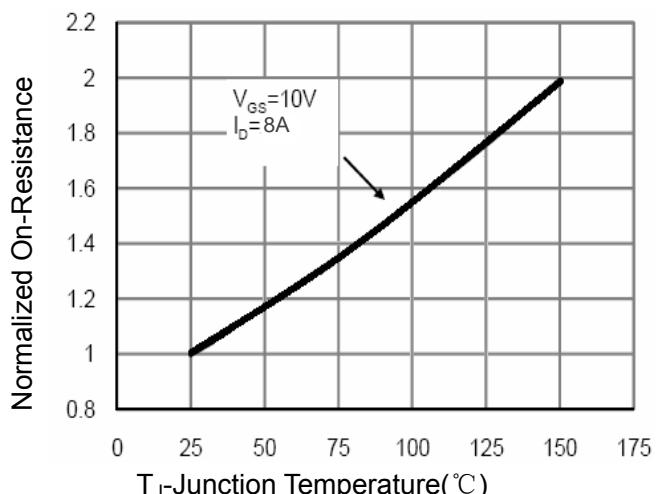


Figure 4 Rdson-JunctionTemperature

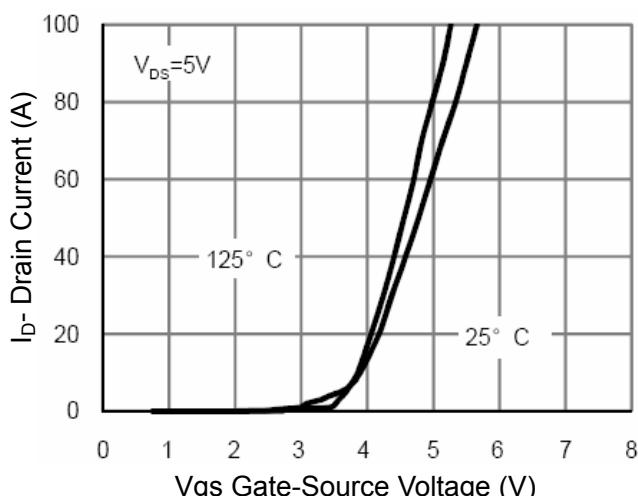


Figure 2 Transfer Characteristics

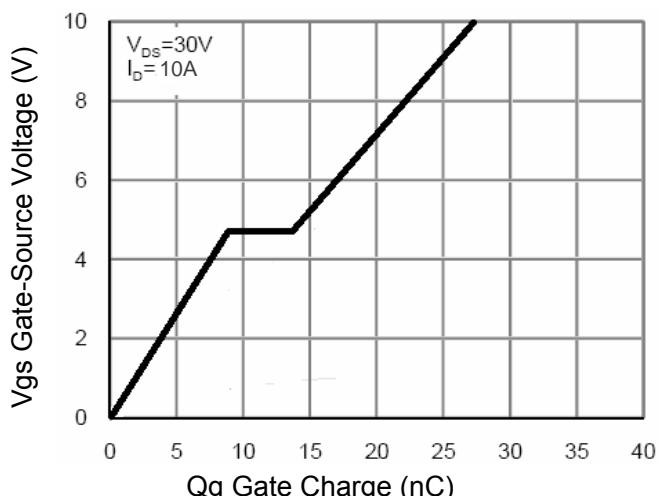


Figure 5 Gate Charge

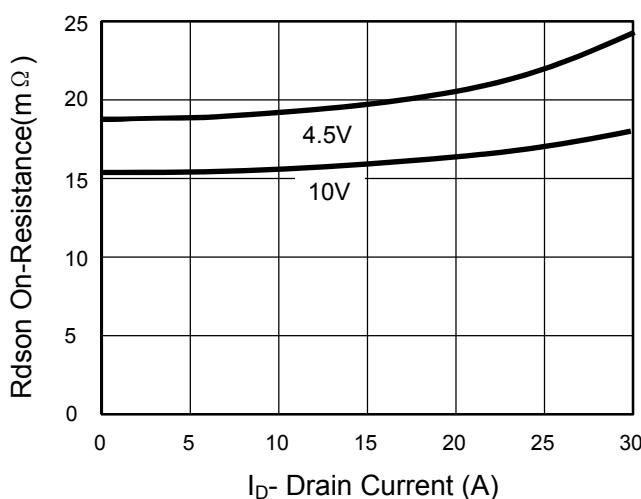


Figure 3 Rdson- Drain Current

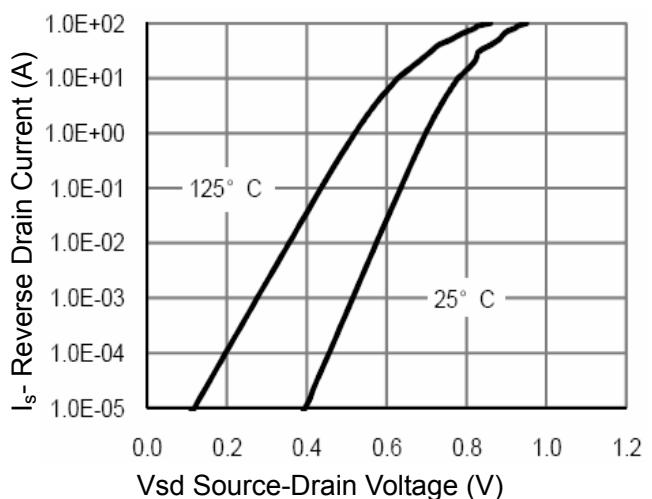


Figure 6 Source- Drain Diode Forward

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD150N04M

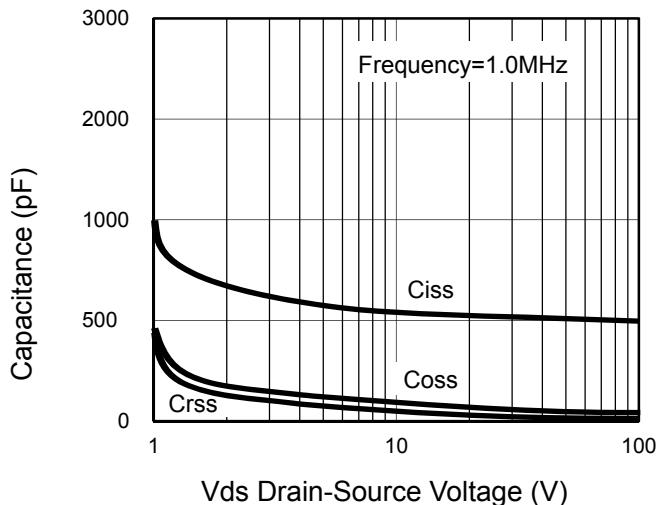


Figure 7 Capacitance vs Vds

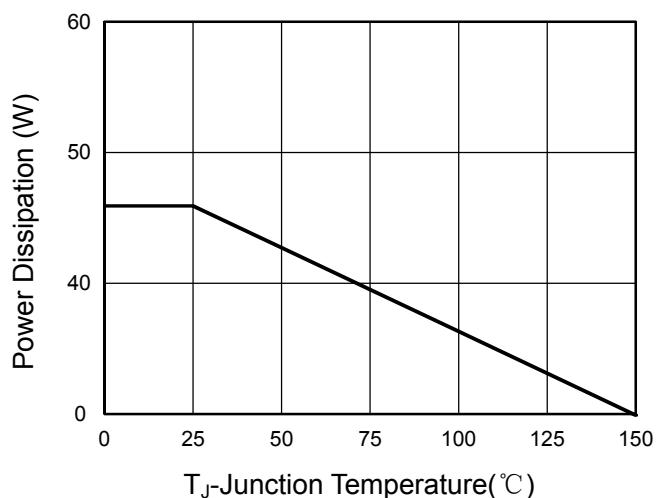


Figure 9 Power De-rating

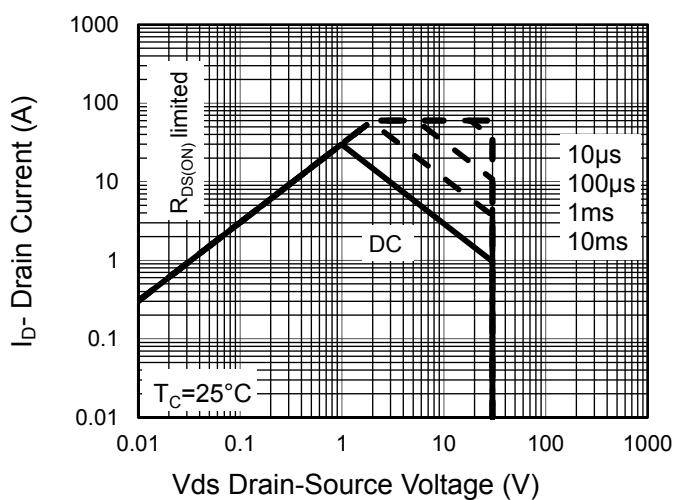


Figure 8 Safe Operation Area

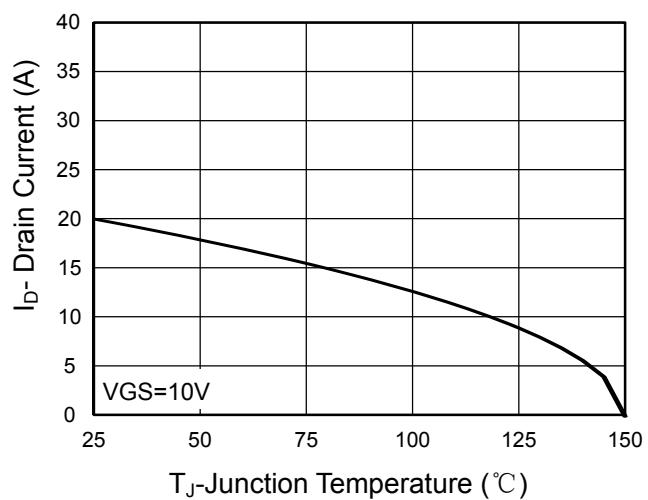


Figure 10 Current De-rating

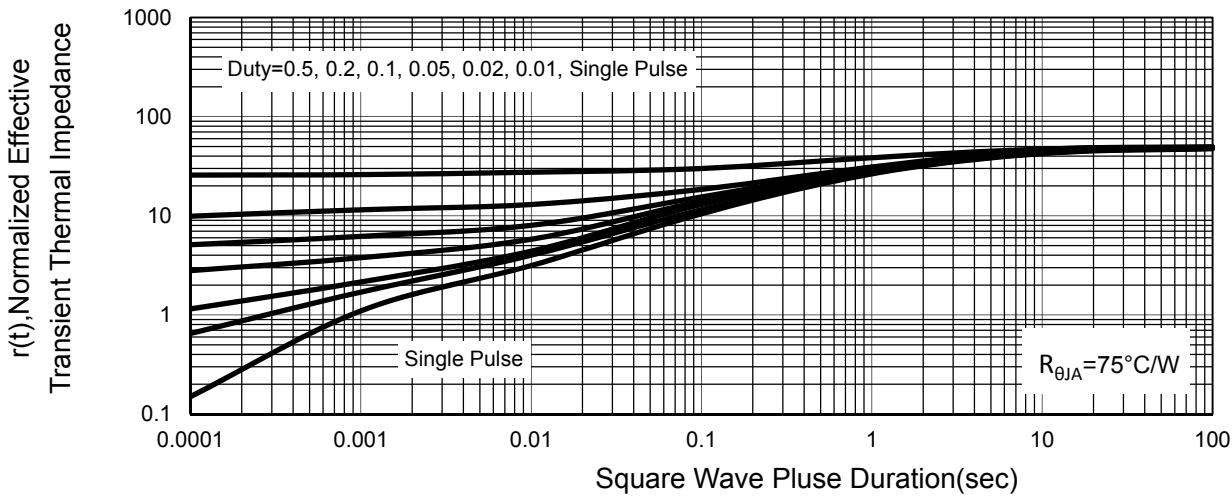


Figure 11 Normalized Maximum Transient Thermal Impedance

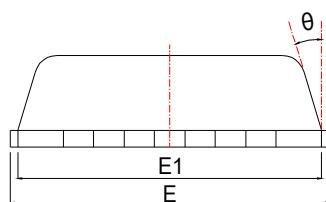
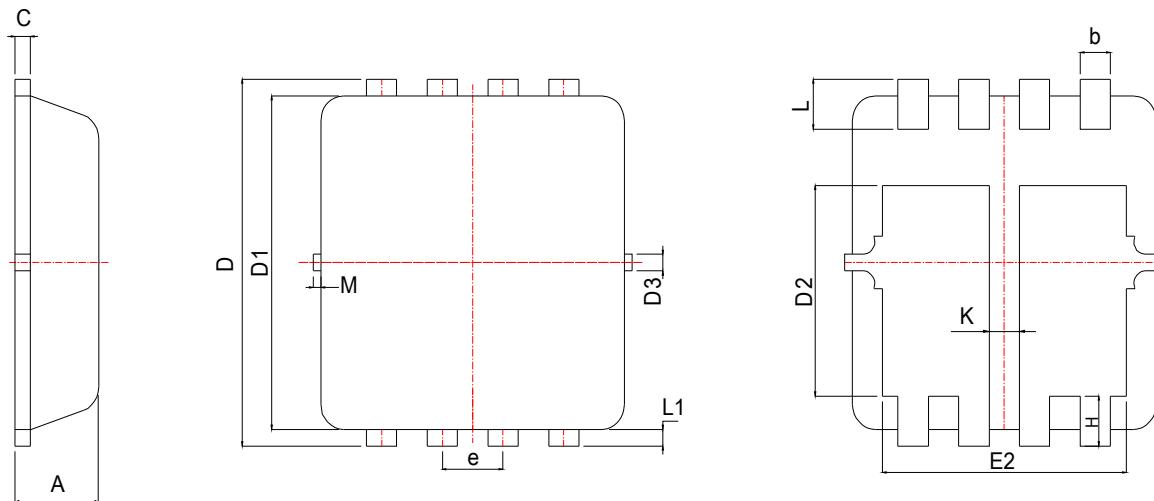
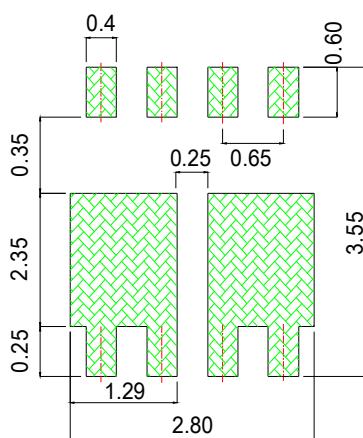


Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TFD150N04M

PDFN3333-8L

Land Pattern
(Only for Reference)

SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031	E1	3.00	3.15	3.20	0.118	0.122	0.126
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.39	2.49	2.59	0.094	0.098	0.102
c	0.10	0.15	0.25	0.004	0.007	0.010	e	0.65BSC			0.026BSC		
D	3.25	3.35	3.45	0.128	0.132	0.136	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.78	1.88	1.98	0.070	0.074	0.078	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	M	*	*	10°	12°	10°	12°
E	3.20	3.30	3.40	0.126	0.130	0.134	θ	*	*	0.15	*	*	0.006
K	0.30	*	*	0.012	*	*							